

HF MODULE FOR T-3000-FC3

HIGH BOND FORCE

HIGH FORCE

MICRO ASSEMBLY

OPTION

HIGH BOND FORCE (HF) module for **TRESKY T-3000** Series with 25 Kg or 50 Kg to meet various bonding technology requirements. The sophisticated design of the HF-module in combination with the TRESKY True Vertical Technology ensures an absolute coplanarity between chip and substrate at any height and force during bonding process. The automated Z-Drive with bond force control enables a high repeatability of bond parameters.

500N Bond Force

Easy to use



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